

Special Issue

Digitalization of Cultural Heritage with Artificial Intelligence: Machine Learning and Deep Learning Solutions

Message from the Guest Editors

The Digitalization of CH represents a fundamental process for the conservation and fruition of cultural goods. Recent technological advances in Geomatics have allowed experts to improve the quality of the digitalization process on the basis of innovative survey technologies. At the same time, the recent development of ML and DL applications has allowed us to make a revolution in the field of segmentation and classification processes in bidimensional and tridimensional domains. This great effort offered by AI represents an innovative possibility for improvements in the CH digitalization process, opening new perspectives for valorization purposes.

- cultural heritage
- TLS
- photogrammetry
- machine learning
- deep learning

Guest Editors

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As the world of science becomes ever more specialized, researchers may lose themselves in the deep forest of the ever increasing number of subfields being created. This open access journal *Applied Sciences* has been started to link these subfields, so researchers can cut through the forest and see the surrounding, or quite distant fields and subfields to help develop his/her own research even further with the aid of this multi-dimensional network.

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